

DSEG 300

DSEG 300 is a 300mm Edge Grip aligner, It has double slots, with gripper chuck to spin the wafer and lift pins to raise wafer to upper slot. Robot swaps unprocessed and processed wafers at the DSEG aligner to save wafer handling steps and improve system throughputs.

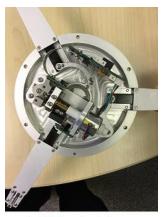
The gripper chuck, with patented soft touch technology, applies constantly monitored force to prevent wafer from over stress.



DSEG 300



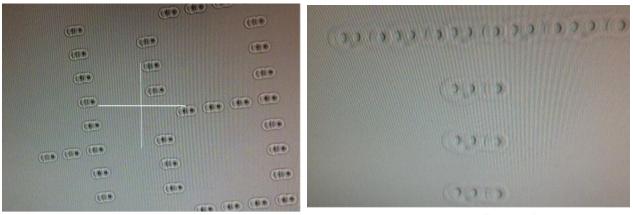
DSEG 300 w/Cognex 1741 OCR



Soft Touch Gripper

DSEG 300 can be retrofitted to replace the ASYST EG-300. With gripper finger fixing and mini-scan, customers benefit better repeatability from DSEG 300 than ASYST EG-300.

Here shows the 20 repeated laser marks on the wafer. The measures of the average dot spans of DSEG 300 are 46 microns (left), but the measures of the average dot spans of ASYST are 72 microns (right).



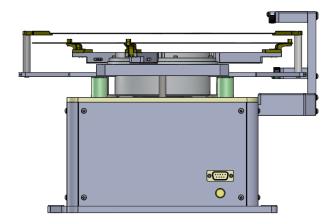
DSEG 300, 20 Repeated Laser Marks

ASYST EG300, 20 Repeated Laser Marks



Specifications:

- 1) Dimensions (mm): 274 x 256 x 221 (h)
- 2) Weight: 6.0kg
- 3) Buffer Station: YES
- 4) Wafer Diameters: 300mm
- 5) Wafer Thickness (mm): > 0.2
- 6) Notch Repeatability (degree): 0.01
- 7) Z Repeatability (mm): 0.05
- 8) Typical Align Time (sec): 10
- 9) Max Align Time (sec): 12
- 10) Buffer Time (sec): 3
- 11) Un-Buffer Time (sec): 3



OCR on ALIGNER

Optionally, Cognex Insight 1741 OCR is integrated on the DSEG 300, which further saves wafer handling steps.

The Cognex 1740 series are capable of reading semi font, OCR-A, IBM, T7, BC412, and IBM412.



DSEG 300 w/Cognex 1741 OCR



Marking Dot Inspection

DSEG 300 optionally integrates Marking Dot Inspection optics to inspect the accuracies of dot positions, dot counts, and residue in the areas between dots.



Marking Dots



DSEG 300 w/Mark Inspection



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